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(54) MANUFACTURE OF FLEXIBLE WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a solderable and flexible wiring board having small dimensional change by heat.

SOLUTION: First, an epoxy-based, polyester-based or acryl-based bonding agent is applied to an insulating film using a comma-coater, and the bonding agent is semicured under a suitable travelling and heating condition. Then, the metal foil such as copper foil, aluminum foil and the like is joined to the adhesive surface of the above-mentioned insulating film using a roll laminator and the like, the bonding agent is cured, and a metal clad board is formed. Then, a prescribed circuit pattern is formed by etching the metal foil. A cover lay is formed on the circuit pattern, a surface treatment is conducted on the exposed circuit pattern, solder plating, nickel plating and gold plating are conducted, and a flexible wiring board is manufactured.

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